

Please send this form
until May 31, 2024

To: **Prof. Akira Kobayashi**
University of Tokyo, Chulalongkorn University
TEL: +81-80-8320-1618, E-mail: iaps-kobayashi@outlook.jp

DATE: _____ /2024
(DD/MM/24)

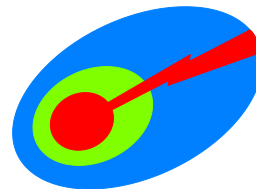
REGISTRATION FORM

The 14th International Symposium on Applied Plasma Science

Date: September 24-28, 2024

Place: Lake Biwa Otsu Prince Hotel, Shiga, Japan

Shiga



ISAPS '24

Name: _____
(First name) (Middle name) (Family name)

Job Title: Prof., Dr., Mr., Ms., Graduate Student, Undergraduate Student

Institution: _____

Mailing Address: _____ City: _____
(Street)

State: _____ Zip code: _____ Country: _____

Phone: _____ Fax: _____

Email: _____

Area of Interest: _____

I plan to participate in the **ISAPS '24**.
Accompanying persons YES NO

I intend to present a paper. (poster presentation for student)
Title: _____

Authors: _____

I plan to reserve the room of the Conference Hotel from _____ to _____
for _____ nights.

I intend to submit a paper to the special issue.

PAYMENT: All payments for pre-registration should be made in **Japanese Yen**.

I will remit the pre-registration fee of _____ yen on _____
(Date)
through _____ to **Sumitomo-Mitsui Banking Corporation,**
(Bank name)
Ibaraki Branch (Account Name: **ISAPS2015**, Account Number: **4195528**).

Other : _____

Signature: _____ Date: _____

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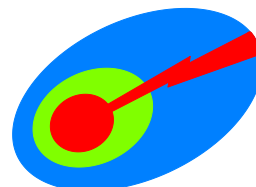
ABSTRACT FORM

The 14th International Symposium on Applied Plasma Science

Date: September 24-28, 2024

Place: Lake Biwa Otsu Prince Hotel, Shiga, Japan

Shiga



ISAPS '24

Name of Authors: _____

Institution: _____

Mailing Address: _____ City: _____
(Street)
State: _____ Zip code: _____ Country: _____
Phone: _____ Fax: _____
Email: _____

Presentation Title: _____

I intend to contribute my paper (4p or 2p) to Conference Book (ADVANCES, Vol. 14) (None submission to the special issue)

I intend to contribute to the special issue of Vacuum or IAPS Journal, etc. (Extended Abstract 1p needed)

Categories: (Check 1 or 2)

- Plasma production, propulsion, diagnostics, modeling & simulations
- Plasma processing (surface modification, deposition, thermal spraying, etc.)
- Plasma applications in microelectronics
- Plasma applications to environmental problems
- Advanced materials (hybrid functionally material, composite materials, etc.)
- Characterization and evaluation of materials
- Industrial applications of directed energy sources (e-beams, ion beams, lasers)

ABSTRACT (within 200 words)

KEYWORDS (~5): _____